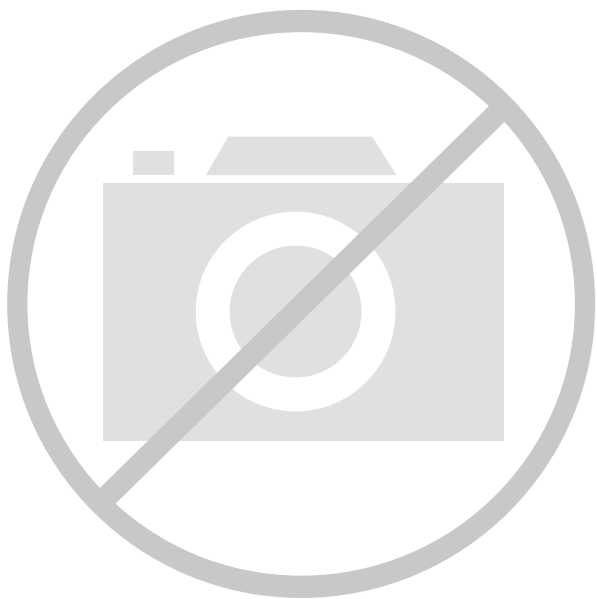




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	147456
Number of I/O	154
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3p1000-pqg208m

I/Os Per Package ¹

ProASIC3/EL Low Power Devices	A3P250		A3PE600L		A3P1000		A3PE3000L	
ARM Cortex-M1 Devices					M1A3P1000		M1A3PE3000L	
Package	Single- Ended I/O ²	Differential I/O Pairs	Single- Ended I/O ²	Differential I/O Pairs	Single- Ended I/O ²	Differential I/O Pairs	Single- Ended I/O ²	Differential I/O Pairs
VQ100	68	13	–	–	–	–	–	–
PQ208	–	–	–	–	154	35	–	–
FG144	–	–	–	–	97	25	–	–
FG256	–	–	–	–	177	44	–	–
FG484	–	–	270	135	300	74	341	168
FG896	–	–	–	–	–	–	620	310

Notes:

- When considering migrating your design to a lower- or higher-density device, refer to the packaging section of the datasheet to ensure you are complying with design and board migration requirements.
- Each used differential I/O pair reduces the number of single-ended I/Os available by two.
- "G" indicates RoHS-compliant packages. Refer to ["Military ProASIC3/EL Ordering Information"](#) on page III for the location of the "G" in the part number.
- For A3PE3000L devices, the usage of certain I/O standards is limited as follows:
 - SSTL3(I) and (II): up to 40 I/Os per north or south bank
 - LVPECL / GTL+ 3.3 V / GTL 3.3 V: up to 48 I/Os per north or south bank
 - SSTL2(I) and (II) / GTL+ 2.5 V / GTL 2.5 V: up to 72 I/Os per north or south bank
- When the Flash*Freeze pin is used to directly enable Flash*Freeze mode and not as a regular I/O, the number of single-ended user I/Os available is reduced by one.

Military ProASIC3/EL Device Status

Military ProASIC3/EL Devices	Status	M1 Military ProASIC3/EL Devices	Status
A3P250	Production		
A3PE600L	Production		
A3P1000	Production	M1A3P1000	Production
A3PE3000L	Production	M1A3PE3000L	Production

1.5 V DC Core Voltage

Table 2-52 • 3.3 V LVTTTL / 3.3 V LVCMOS Low Slew

Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.61	5.90	0.04	1.45	2.09	0.40	5.98	4.73	2.52	2.24	7.45	6.19	ns
	–1	0.52	5.02	0.03	1.23	1.78	0.34	5.09	4.02	2.15	1.90	6.34	5.27	ns
8 mA	Std.	0.61	4.80	0.04	1.45	2.09	0.40	4.86	4.02	2.87	2.85	6.32	5.49	ns
	–1	0.52	4.08	0.03	1.23	1.78	0.34	4.13	3.42	2.44	2.43	5.38	4.67	ns
12 mA	Std.	0.61	4.02	0.04	1.45	2.09	0.40	4.06	3.49	3.09	3.23	5.53	4.96	ns
	–1	0.52	3.42	0.03	1.23	1.78	0.34	3.46	2.97	2.63	2.75	4.70	4.22	ns
16 mA	Std.	0.61	3.79	0.04	1.45	2.09	0.40	3.84	3.38	3.14	3.34	5.30	4.84	ns
	–1	0.52	3.23	0.03	1.23	1.78	0.34	3.26	2.87	2.67	2.84	4.51	4.12	ns
24 mA	Std.	0.61	3.67	0.04	1.45	2.09	0.40	3.72	3.39	3.20	3.74	5.18	4.86	ns
	–1	0.52	3.13	0.03	1.23	1.78	0.34	3.16	2.88	2.72	3.18	4.41	4.13	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-53 • 3.3 V LVTTTL / 3.3 V LVCMOS High Slew

Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 3.0\text{ V}$

Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
4 mA	Std.	0.61	3.26	0.04	1.45	2.09	0.40	3.30	2.48	2.52	2.38	4.76	3.95	ns
	–1	0.52	2.77	0.03	1.23	1.78	0.34	2.80	2.11	2.15	2.03	4.05	3.36	ns
8 mA	Std.	0.61	2.66	0.04	1.45	2.09	0.40	2.68	1.97	2.87	3.00	4.15	3.43	ns
	–1	0.52	2.26	0.03	1.23	1.78	0.34	2.28	1.67	2.44	2.55	3.53	2.92	ns
12 mA	Std.	0.61	2.32	0.04	1.45	2.09	0.40	2.33	1.72	3.09	3.40	3.80	3.18	ns
	–1	0.52	1.97	0.03	1.23	1.78	0.34	1.99	1.46	2.63	2.89	3.23	2.71	ns
16 mA	Std.	0.61	2.26	0.04	1.45	2.09	0.40	2.28	1.67	3.15	3.51	3.74	3.14	ns
	–1	0.52	1.92	0.03	1.23	1.78	0.34	1.94	1.42	2.68	2.98	3.18	2.67	ns
24 mA	Std.	0.61	2.28	0.04	1.45	2.09	0.40	2.30	1.61	3.21	3.90	3.77	3.07	ns
	–1	0.52	1.94	0.03	1.23	1.78	0.34	1.96	1.37	2.73	3.32	3.20	2.61	ns

Notes:

- Software default selection highlighted in gray.
- For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

HSTL Class II

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). Military ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-140 • Minimum and Maximum DC Input and Output Levels

HSTL Class II	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IL ¹	I _{IH} ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
15 mA ⁵	−0.3	VREF − 0.1	VREF + 0.1	3.6	0.4	VCCI − 0.4	15	15	66	55	15	15

Notes:

- I_{IL} is the input leakage current per I/O pin over recommended operating conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
- I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
- Currents are measured at 100°C junction temperature and maximum voltage.
- Currents are measured at 125°C junction temperature.
- Output drive strength is below JEDEC specification.

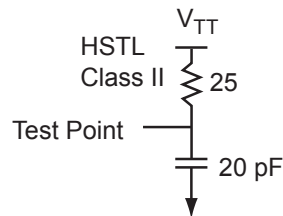


Figure 2-20 • AC Loading

Table 2-141 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C _{LOAD} (pF)
VREF − 0.1	VREF + 0.1	0.75	0.75	0.75	20

Note: *Measuring point = Vtrip. See Table 2-29 on page 2-25 for a complete table of trip points.

Timing Characteristics

Table 2-142 • HSTL Class II

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case VCC = 1.14 V,
Worst-Case VCCI = 1.4 V, VREF = 0.75 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.80	3.00	0.05	2.76	0.52	3.05	2.69	—	—	5.25	4.89	ns
−1	0.68	2.55	0.05	2.34	0.44	2.59	2.28	—	—	4.47	4.16	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-151 • SSTL2 Class II

Military-Case Conditions: $T_J = 125^\circ\text{C}$, $V_{CC} = 1.425\text{ V}$,
Worst-Case $V_{CCI} = 2.3\text{ V}$, $V_{REF} = 1.25\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.61	2.02	0.04	1.85	0.40	2.03	1.64	—	—	2.03	1.64	ns
–1	0.52	1.72	0.03	1.58	0.34	1.73	1.39	—	—	1.73	1.39	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

SSTL3 Class I

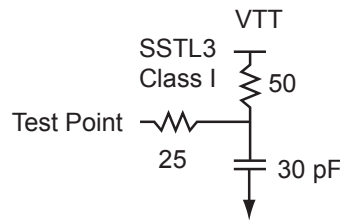
Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). Military ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-152 • Minimum and Maximum DC Input and Output Levels

SSTL3 Class I	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}	I_{OSL}	I_{OSH}	I_{IL}^1	I_{IH}^2
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA^4	μA^4
14 mA	–0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCI} - 1.1$	14	14	51	54	15	15

Notes:

- I_{IL} is the input leakage current per I/O pin over recommended operating conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
- I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
- Currents are measured at 100°C junction temperature and maximum voltage.
- Currents are measured at 125°C junction temperature.


Figure 2-23 • AC Loading
Table 2-153 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.2$	$V_{REF} + 0.2$	1.5	1.5	1.485	30

Note: *Measuring point = V_{trip} . See [Table 2-29 on page 2-25](#) for a complete table of trip points.

Timing Characteristics

Table 2-154 • SSTL3 Class I

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$, $V_{REF} = 1.5\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.80	2.29	0.05	2.00	0.52	2.32	1.82	—	—	2.32	1.82	ns
–1	0.68	1.95	0.05	1.71	0.44	1.98	1.55	—	—	1.98	1.55	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-155 • SSTL3 Class I

Military-Case Conditions: $T_J = 125^\circ\text{C}$, $V_{CC} = 1.425\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$, $V_{REF} = 1.5\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.61	2.15	0.04	1.77	0.40	2.17	1.70	—	—	2.17	1.70	ns
–1	0.52	1.83	0.03	1.51	0.34	1.84	1.45	—	—	1.84	1.45	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

SSTL3 Class II

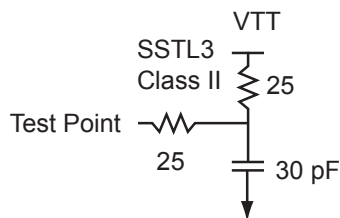
Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). Military ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-156 • Minimum and Maximum DC Input and Output Levels

SSTL3 Class II	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL	IIH
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ¹	Max. mA ¹	μA ²	μA ²
21 mA	–0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCI} - 0.9$	21	21	103	109	15	15

Notes:

1. Currents are measured at 100°C junction temperature and maximum voltage.
2. Currents are measured at 125°C junction temperature.


Figure 2-24 • AC Loading
Table 2-157 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	V_{REF} (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
$V_{REF} - 0.2$	$V_{REF} + 0.2$	1.5	1.5	1.485	30

Note: *Measuring point = V_{trip} . See Table 2-29 on page 2-25 for a complete table of trip points.

Timing Characteristics

Table 2-158 • SSTL3 Class II

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$,
Worst-Case $V_{CCI} = 3.0\text{ V}$, $V_{REF} = 1.5\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.80	2.05	0.05	2.00	0.52	2.08	1.65	—	—	2.08	1.65	ns
–1	0.68	1.75	0.05	1.71	0.44	1.77	1.41	—	—	1.77	1.41	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-174 • Input Data Register Propagation Delays
Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$ for A3P250 and A3P1000

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Input Data Register	0.29	0.34	ns
t_{SUD}	Data Setup Time for the Input Data Register	0.32	0.37	ns
t_{IHD}	Data Hold Time for the Input Data Register	0.00	0.00	ns
t_{ISUE}	Enable Setup Time for the Input Data Register	0.45	0.53	ns
t_{IHE}	Enable Hold Time for the Input Data Register	0.00	0.00	ns
t_{CLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.55	0.64	ns
t_{PRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.55	0.64	ns
t_{REMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	0.00	ns
t_{RECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.27	0.31	ns
t_{REMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	0.00	ns
t_{RECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.27	0.31	ns
t_{WCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.25	0.30	ns
t_{WPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.25	0.30	ns
t_{CKMPWH}	Clock Minimum Pulse Width HIGH for the Input Data Register	0.41	0.48	ns
t_{CKMPWL}	Clock Minimum Pulse Width LOW for the Input Data Register	0.37	0.43	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

Output Enable Register

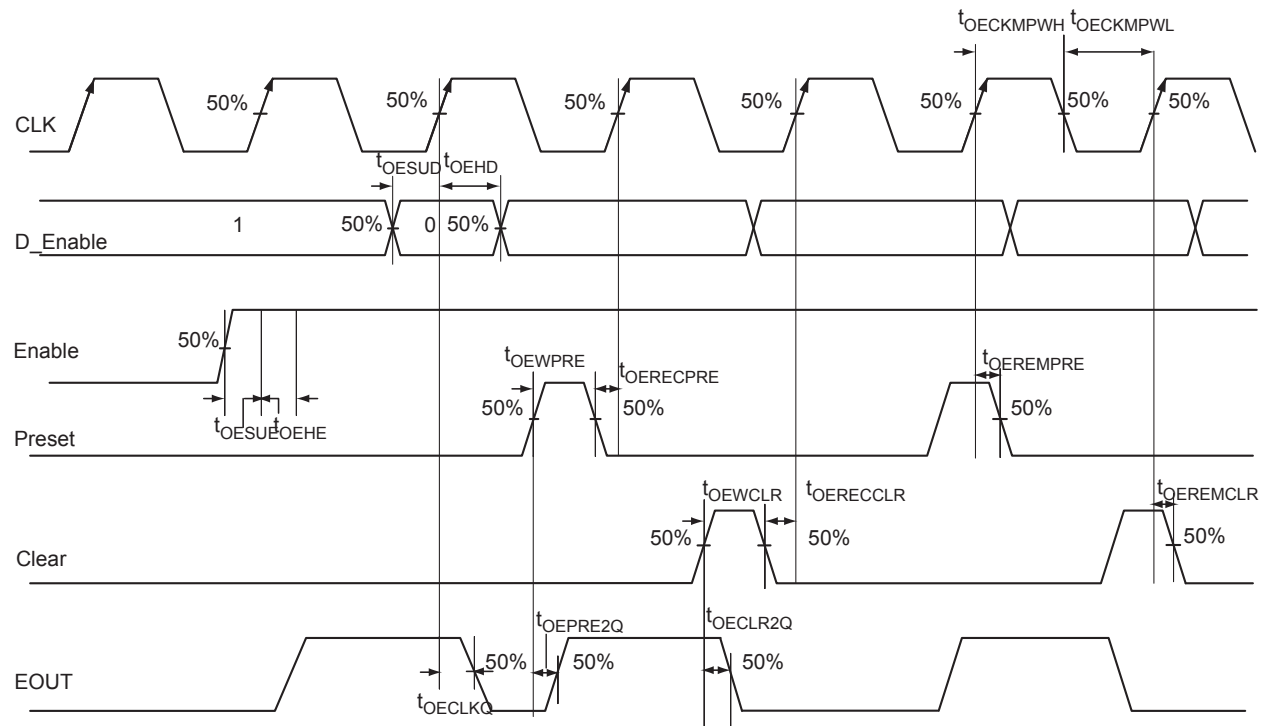


Figure 2-32 • Output Enable Register Timing Diagram

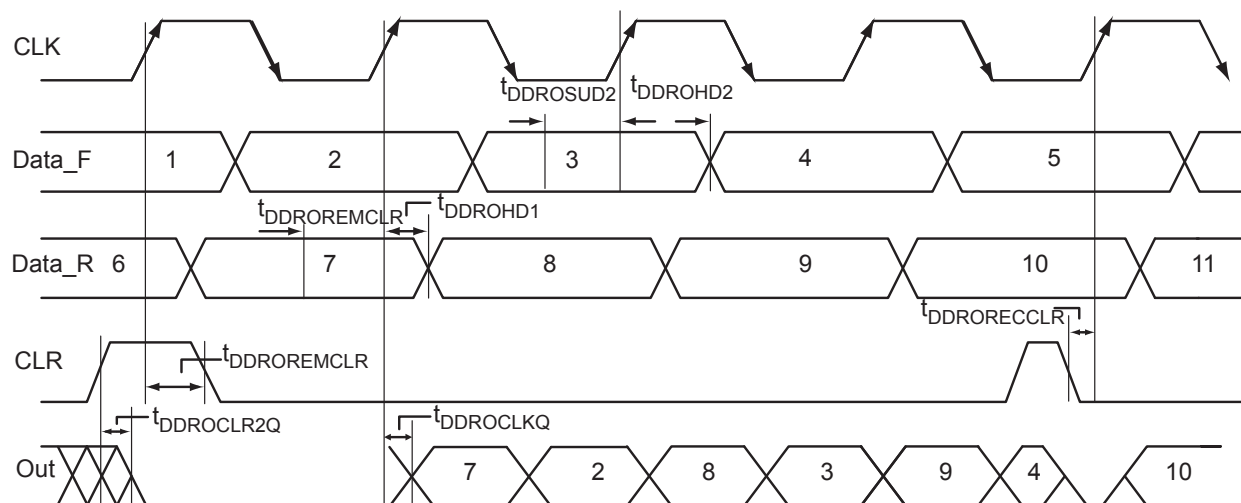


Figure 2-36 • Output DDR Timing Diagram

Timing Characteristics

Table 2-186 • Output DDR Propagation Delays

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case $V_{CC} = 1.14\text{ V}$ for A3PE600L and A3PE3000L

Parameter	Description	–1	Std.	Units
t_{DDROCLKQ}	Clock-to-Out of DDR for Output DDR	0.97	1.14	ns
t_{DDRISUD1}	Data_F Data Setup for Output DDR	0.52	0.62	ns
t_{DDROSUD2}	Data_R Data Setup for Output DDR	0.52	0.62	ns
t_{DDROHD1}	Data_F Data Hold for Output DDR	0.00	0.00	ns
t_{DDROHD2}	Data_R Data Hold for Output DDR	0.00	0.00	ns
$t_{\text{DDROCLR2Q}}$	Asynchronous Clear-to-Out for Output DDR	1.11	1.30	ns
$t_{\text{DDROEMCLR}}$	Asynchronous Clear Removal Time for Output DDR	0.00	0.00	ns
$t_{\text{DDROECCLR}}$	Asynchronous Clear Recovery Time for Output DDR	0.31	0.36	ns
$t_{\text{DDROWCLR1}}$	Asynchronous Clear Minimum Pulse Width for Output DDR	0.19	0.22	ns
$t_{\text{DDROCKMPWH}}$	Clock Minimum Pulse Width HIGH for the Output DDR	0.31	0.36	ns
$t_{\text{DDROCKMPWL}}$	Clock Minimum Pulse Width LOW for the Output DDR	0.28	0.32	ns
F_{DDROMAX}	Maximum Frequency for the Output DDR	160	160	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-191 • Combinatorial Cell Propagation Delays

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case $V_{CC} = 1.425\text{ V}$ for A3P250 and A3P1000

Combinatorial Cell	Equation	Parameter	–1	Std.	Units
INV	$Y = !A$	t_{PD}	0.48	0.57	ns
AND2	$Y = A \cdot B$	t_{PD}	0.57	0.67	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	0.57	0.67	ns
OR2	$Y = A + B$	t_{PD}	0.59	0.69	ns
NOR2	$Y = !(A + B)$	t_{PD}	0.59	0.69	ns
XOR2	$Y = A \oplus B$	t_{PD}	0.89	1.04	ns
MAJ3	$Y = \text{MAJ}(A, B, C)$	t_{PD}	0.84	0.99	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	1.05	1.24	ns
MUX2	$Y = A !S + B S$	t_{PD}	0.61	0.72	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	0.68	0.79	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

Table 2-193 • Register Delays
Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$ for A3PE600L and A3PE3000L

Parameter	Description	–1	Std.	Units
t_{CLKQ}	Clock-to-Q of the Core Register	0.58	0.69	ns
t_{SUD}	Data Setup Time for the Core Register	0.45	0.53	ns
t_{HD}	Data Hold Time for the Core Register	0.00	0.00	ns
t_{SUE}	Enable Setup Time for the Core Register	0.48	0.57	ns
t_{HE}	Enable Hold Time for the Core Register	0.00	0.00	ns
t_{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.42	0.50	ns
t_{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.42	0.50	ns
t_{REMCLR}	Asynchronous Clear Removal Time for the Core Register	0.00	0.00	ns
t_{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.24	0.28	ns
t_{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	0.00	ns
t_{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.24	0.28	ns
t_{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.30	0.34	ns
t_{CKMPWH}	Clock Minimum Pulse Width HIGH for the Core Register	0.56	0.64	ns
t_{CKMPWL}	Clock Minimum Pulse Width LOW for the Core Register	0.56	0.64	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Global Resource Characteristics

A3P1000 Clock Tree Topology

Clock delays are device-specific. Figure 2-41 is an example of a global tree used for clock routing. The global tree presented in Figure 2-41 is driven by a CCC located on the west side of the A3P1000 device. It is used to drive all D-flip-flops in the device.

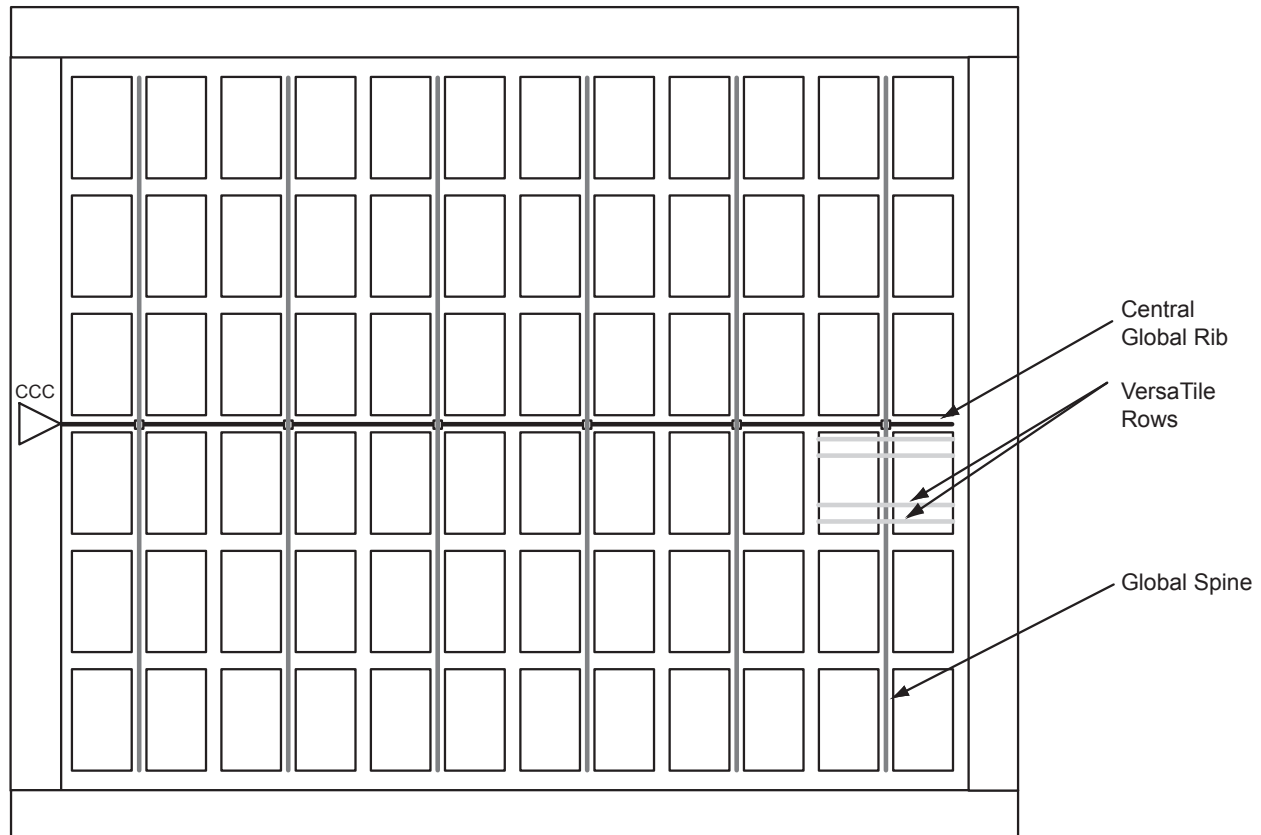


Figure 2-41 • Example of Global Tree Use in an A3P1000 Device for Clock Routing

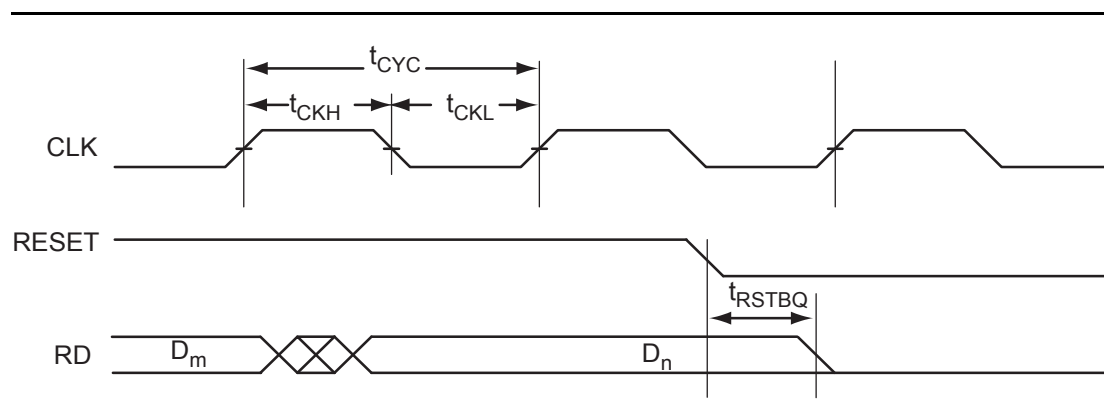


Figure 2-48 • RAM Reset

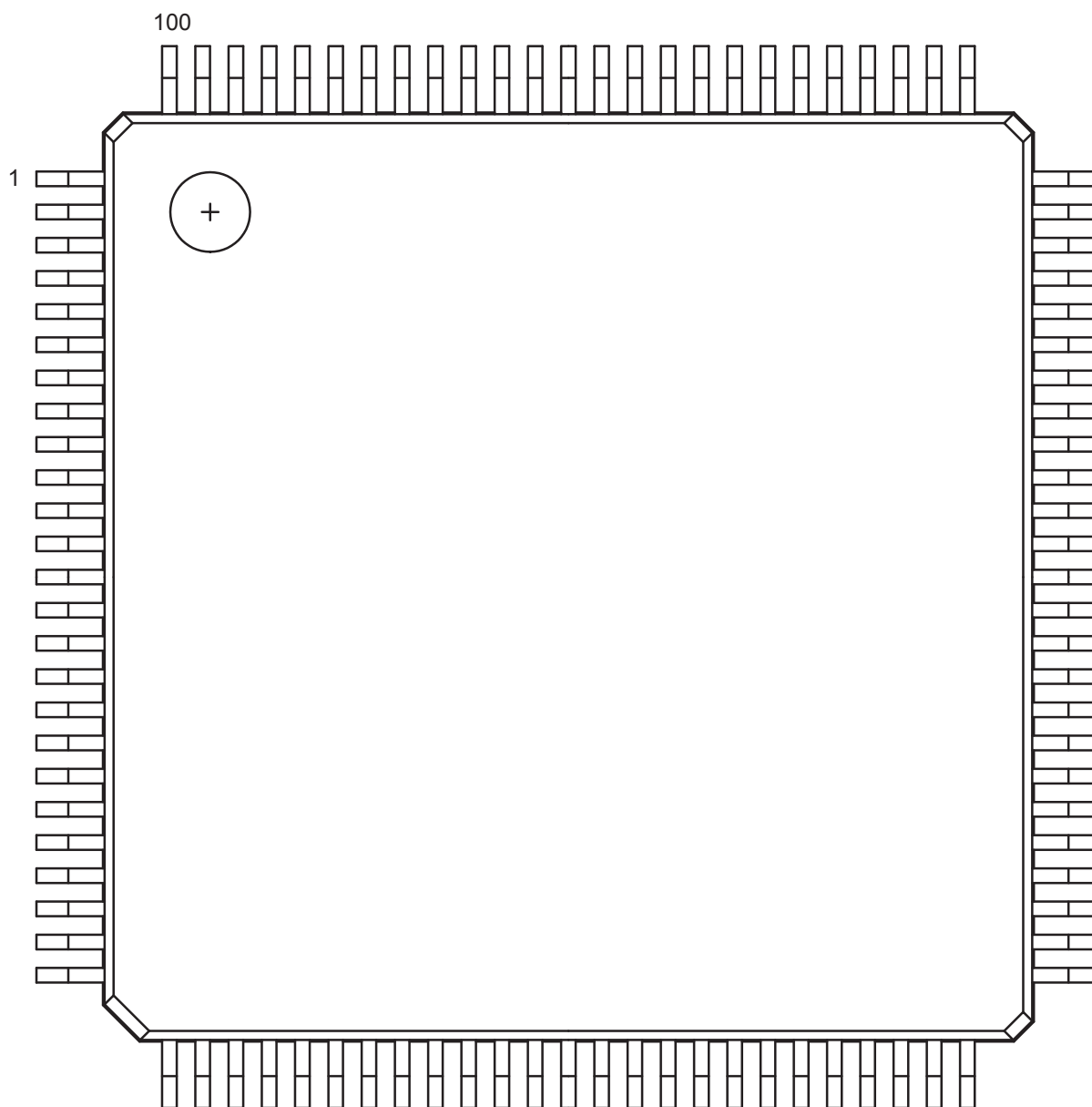
Table 2-211 • FIFO Worst Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$ for A3P1000

Parameter	Description	–1	Std.	Units
t_{ENS}	REN, WEN Setup Time	1.66	1.95	ns
t_{ENH}	REN, WEN Hold Time	0.00	0.00	ns
t_{BKS}	BLK Setup Time	1.66	1.95	ns
t_{BKH}	BLK Hold Time	0.00	0.00	ns
t_{DS}	Input Data (WD) Setup Time	0.22	0.26	ns
t_{DH}	Input Data (WD) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to New Data Valid on RD (flow-through)	2.84	3.33	ns
t_{CKQ2}	Clock HIGH to New Data Valid on RD (pipelined)	1.08	1.27	ns
t_{RCKEF}	RCLK HIGH to Empty Flag Valid	2.07	2.43	ns
t_{WCKFF}	WCLK HIGH to Full Flag Valid	1.96	2.31	ns
t_{CKAF}	Clock HIGH to Almost Empty/Full Flag Valid	7.45	8.76	ns
t_{RSTFG}	RESET LOW to Empty/Full Flag Valid	2.04	2.40	ns
t_{RSTAF}	RESET LOW to Almost Empty/Full Flag Valid	7.38	8.67	ns
t_{RSTBQ}	RESET LOW to Data Out LOW on RD (flow-through)	1.11	1.31	ns
	RESET LOW to Data Out LOW on RD (pipelined)	1.11	1.31	ns
t_{REMRSTB}	RESET Removal	0.34	0.40	ns
t_{RECRSTB}	RESET Recovery	1.81	2.12	ns
t_{MPWRSTB}	RESET Minimum Pulse Width	0.26	0.30	ns
t_{CYC}	Clock Cycle Time	3.89	4.57	ns
F_{MAX}	Maximum Frequency for FIFO	257	219	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

4 – Package Pin Assignments

VQ100



Note: This is the top view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.microsemi.com/products/fpga-soc/solutions>.

FG484		FG484		FG484	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
N8	VCCIB6	P21	IO130PDB3V2	T12	IO194NDB5V0
N9	VCC	P22	IO128NDB3V1	T13	IO186NDB4V4
N10	GND	R1	IO247NDB6V1	T14	IO186PDB4V4
N11	GND	R2	IO245PDB6V1	T15	GNDQ
N12	GND	R3	VCC	T16	VCOMPLD
N13	GND	R4	IO249NPB6V1	T17	VJTAG
N14	VCC	R5	IO251NDB6V2	T18	GDC0/IO151NDB3V4
N15	VCCIB3	R6	IO251PDB6V2	T19	GDA1/IO153PDB3V4
N16	IO116NPB3V0	R7	GEC0/IO236NPB6V0	T20	IO144PDB3V3
N17	IO132NPB3V2	R8	VMV5	T21	IO140PDB3V3
N18	IO117NPB3V0	R9	VCCIB5	T22	IO134NDB3V2
N19	IO132PPB3V2	R10	VCCIB5	U1	IO240PPB6V0
N20	GNDQ	R11	IO196NDB5V0	U2	IO238PDB6V0
N21	IO126NDB3V1	R12	IO196PDB5V0	U3	IO238NDB6V0
N22	IO128PDB3V1	R13	VCCIB4	U4	GEB1/IO235PDB6V0
P1	IO247PDB6V1	R14	VCCIB4	U5	GEB0/IO235NDB6V0
P2	IO253PDB6V2	R15	VMV3	U6	VMV6
P3	IO270NPB6V4	R16	VCCPLD	U7	VCCPLE
P4	IO261NPB6V3	R17	GDB1/IO152PPB3V4	U8	IO233NPB5V4
P5	IO249PPB6V1	R18	GDC1/IO151PDB3V4	U9	IO222PPB5V3
P6	IO259PDB6V3	R19	IO138NDB3V3	U10	IO206PDB5V1
P7	IO259NDB6V3	R20	VCC	U11	IO202PDB5V1
P8	VCCIB6	R21	IO130NDB3V2	U12	IO194PDB5V0
P9	GND	R22	IO134PDB3V2	U13	IO176NDB4V2
P10	VCC	T1	IO243PPB6V1	U14	IO176PDB4V2
P11	VCC	T2	IO245NDB6V1	U15	VMV4
P12	VCC	T3	IO243NPB6V1	U16	TCK
P13	VCC	T4	IO241PDB6V0	U17	VPUMP
P14	GND	T5	IO241NDB6V0	U18	TRST
P15	VCCIB3	T6	GEC1/IO236PPB6V0	U19	GDA0/IO153NDB3V4
P16	GDB0/IO152NPB3V4	T7	VCOMPLE	U20	IO144NDB3V3
P17	IO136NDB3V2	T8	GNDQ	U21	IO140NDB3V3
P18	IO136PDB3V2	T9	GEA2/IO233PPB5V4	U22	IO142PDB3V3
P19	IO138PDB3V3	T10	IO206NDB5V1	V1	IO239PDB6V0
P20	VMV3	T11	IO202NDB5V1	V2	IO240NPB6V0

FG896	
Pin Number	A3PE3000L Function
AC21	IO164PDB4V1
AC22	IO162PPB4V1
AC23	GND
AC24	VCOMPLD
AC25	IO150NDB3V4
AC26	IO148NDB3V4
AC27	GDA1/IO153PDB3V4
AC28	IO145NDB3V3
AC29	IO143NDB3V3
AC30	IO137NDB3V2
AD1	GND
AD2	IO242NPB6V1
AD3	IO240NDB6V0
AD4	GEC0/IO236NDB6V0
AD5	VCCIB6
AD6	GNDQ
AD6	GNDQ
AD7	VCC
AD8	VMV5
AD9	VCCIB5
AD10	IO224PPB5V3
AD11	IO218NPB5V3
AD12	IO216PPB5V2
AD13	IO210PPB5V2
AD14	IO202PPB5V1
AD15	IO194PDB5V0
AD16	IO190PDB4V4
AD17	IO182NPB4V3
AD18	IO176NDB4V2
AD19	IO176PDB4V2
AD20	IO170PPB4V2
AD21	IO166PDB4V1
AD22	VCCIB4
AD23	TCK
AD24	VCC
AD25	TRST

FG896	
Pin Number	A3PE3000L Function
AD26	VCCIB3
AD27	GDA0/IO153NDB3V4
AD28	GDC0/IO151NDB3V4
AD29	GDC1/IO151PDB3V4
AD30	GND
AE1	IO242PPB6V1
AE2	VCC
AE3	IO239PDB6V0
AE4	IO239NDB6V0
AE5	VMV6
AE5	VMV6
AE6	GND
AE7	GNDQ
AE8	IO230NDB5V4
AE9	IO224NPB5V3
AE10	IO214NPB5V2
AE11	IO212NDB5V2
AE12	IO212PDB5V2
AE13	IO202NPB5V1
AE14	IO200NDB5V0
AE15	IO196PDB5V0
AE16	IO190NDB4V4
AE17	IO184PDB4V3
AE18	IO184NDB4V3
AE19	IO172PDB4V2
AE20	IO172NDB4V2
AE21	IO166NDB4V1
AE22	IO160PDB4V0
AE23	GNDQ
AE24	VMV4
AE25	GND
AE26	GDB0/IO152NDB3V4
AE27	GDB1/IO152PDB3V4
AE28	VMV3
AE28	VMV3
AE29	VCC

FG896	
Pin Number	A3PE3000L Function
AE30	IO149PDB3V4
AF1	GND
AF2	IO238PPB6V0
AF3	VCCIB6
AF4	IO220NPB5V3
AF5	VCC
AF6	IO228NDB5V4
AF7	VCCIB5
AF8	IO230PDB5V4
AF9	IO229NDB5V4
AF10	IO229PDB5V4
AF11	IO214PPB5V2
AF12	IO208NDB5V1
AF13	IO208PDB5V1
AF14	IO200PDB5V0
AF15	IO196NDB5V0
AF16	IO186NDB4V4
AF17	IO186PDB4V4
AF18	IO180NDB4V3
AF19	IO180PDB4V3
AF20	IO168NDB4V1
AF21	IO168PDB4V1
AF22	IO160NDB4V0
AF23	IO158NPB4V0
AF24	VCCIB4
AF25	IO154NPB4V0
AF26	VCC
AF27	TDO
AF28	VCCIB3
AF29	GNDQ
AF29	GNDQ
AF30	GND
AG1	IO238NPB6V0
AG2	VCC
AG3	IO232NPB5V4
AG4	GND

FG896	
Pin Number	A3PE3000L Function
H26	IO84NDB2V0
H27	IO96PDB2V1
H28	IO96NDB2V1
H29	IO89PDB2V0
H30	IO89NDB2V0
J1	IO290NDB7V2
J2	IO290PDB7V2
J3	IO302NDB7V3
J4	IO302PDB7V3
J5	IO295NDB7V2
J6	IO299NDB7V3
J7	VCCIB7
J8	VCCPLA
J9	VCC
J10	IO04NPB0V0
J11	IO18NDB0V2
J12	IO20NDB0V2
J13	IO20PDB0V2
J14	IO32NDB0V3
J15	IO32PDB0V3
J16	IO42PDB1V0
J17	IO44NDB1V0
J18	IO44PDB1V0
J19	IO54NDB1V1
J20	IO54PDB1V1
J21	IO76NPB1V4
J22	VCC
J23	VCCPLB
J24	VCCIB2
J25	IO90PDB2V1
J26	IO90NDB2V1
J27	GBB2/IO83PDB2V0
J28	IO83NDB2V0
J29	IO91PDB2V1
J30	IO91NDB2V1
K1	IO288NDB7V1

FG896	
Pin Number	A3PE3000L Function
K2	IO288PDB7V1
K3	IO304NDB7V3
K4	IO304PDB7V3
K5	GAB2/IO308PDB7V4
K6	IO308NDB7V4
K7	IO301PDB7V3
K8	IO301NDB7V3
K9	GAC2/IO307PPB7V4
K10	VCC
K11	IO04PPB0V0
K12	VCCIB0
K13	VCCIB0
K14	VCCIB0
K15	VCC IB0
K16	VCCIB1
K17	VCCIB1
K18	VCCIB1
K19	VCCIB1
K20	IO76PPB1V4
K21	VCC
K22	IO78PPB1V4
K23	IO88NDB2V0
K24	IO88PDB2V0
K25	IO94PDB2V1
K26	IO94NDB2V1
K27	IO85PDB2V0
K28	IO85NDB2V0
K29	IO93PDB2V1
K30	IO93NDB2V1
L1	IO286NDB7V1
L2	IO286PDB7V1
L3	IO298NDB7V3
L4	IO298PDB7V3
L5	IO283PDB7V1
L6	IO291NDB7V2
L7	IO291PDB7V2

FG896	
Pin Number	A3PE3000L Function
P26	IO111NPB2V3
P27	IO105PDB2V2
P28	IO105NDB2V2
P29	GCC2/IO117PDB3V0
P30	IO117NDB3V0
R1	GFC2/IO270PDB6V4
R2	GFB1/IO274PPB7V0
R3	VCOMPLF
R4	GFA0/IO273NDB6V4
R5	GFB0/IO274NPB7V0
R6	IO271NDB6V4
R7	GFB2/IO271PDB6V4
R8	IO269PDB6V4
R9	IO269NDB6V4
R10	VCCIB7
R11	VCC
R12	GND
R13	GND
R14	GND
R15	GND
R16	GND
R17	GND
R18	GND
R19	GND
R20	VCC
R21	VCCIB2
R22	GCC0/IO112NDB2V3
R23	GCB2/IO116PDB3V0
R24	IO118PDB3V0
R25	IO111PPB2V3
R26	IO122PPB3V1
R27	GCA0/IO114NPB3V0
R28	VCOMPLC
R29	GCB1/IO113PPB2V3
R30	IO115NPB3V0
T1	IO270NDB6V4

FG896	
Pin Number	A3PE3000L Function
V14	GND
V15	GND
V16	GND
V17	GND
V18	GND
V19	GND
V20	VCC
V21	VCCIB3
V22	IO120NDB3V0
V23	IO128NDB3V1
V24	IO132PDB3V2
V25	IO130PPB3V2
V26	IO126NDB3V1
V27	IO129NDB3V1
V28	IO127NDB3V1
V29	IO125NDB3V1
V30	IO123PDB3V1
W1	IO266NDB6V4
W2	IO262NDB6V3
W3	IO260NDB6V3
W4	IO252NDB6V2
W5	IO251NDB6V2
W6	IO251PDB6V2
W7	IO255NDB6V2
W8	IO249PPB6V1
W9	IO253PDB6V2
W10	VCCIB6
W11	VCC
W12	GND
W13	GND
W14	GND
W15	GND
W16	GND
W17	GND
W18	GND
W19	GND